

Power line chokes

Current-compensated ring core double chokes
600 V AC / 1000 V DC, 0.42 ... 3.3 mH, 20 ... 50 A, +70 °C

Series/Type: **B8272*E6**

Date: **May 2015**

Current-compensated ring core double chokes
Rated voltage 600 V AC / 1000 V DC
Rated inductance 0.42 ... 3.3 mH
Rated current 20 ... 50 A / +70 °C
Construction

- Current-compensated ring core double choke
- Ferrite core
- Plastic core case incl. spacer (UL 94 V-0, CTI600)
- Plastic base plate (UL 94 V-0)
- Sector winding
- Clearance and creepage distances ≥ 8 mm

Features

- Insulation for high voltage applications
- Approx. 0.6 ... 0.8% stray inductance for symmetrical interference suppression
- Wide range of values due to 3 core sizes
- High rated current and rated temperature
- Suitable for wave soldering
- Design complies with EN 60938-2 (VDE 0565-2)
- UL 1446 class 155 (F) electrical insulation system
- Recyclable owing to omission of adhesives
- RoHS-compatible

Applications

- Suppression of common-mode interferences
- High-voltage switch-mode power applications
- Power inverters
- Frequency converters

Terminals

- Ends of winding wires
- Hot-dip tinned

Marking

Product brand, electrical insulation system designation, ordering code, rated voltages, rated inductance, rated current, date of manufacture (YYWWD.internal ID code), production place identification code

Delivery mode

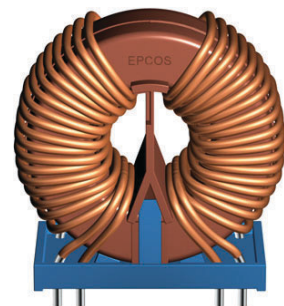
- Cardboard box



Size A



Size B



Size C

Current-compensated ring core double chokes

Dimensional drawings and pin configurations

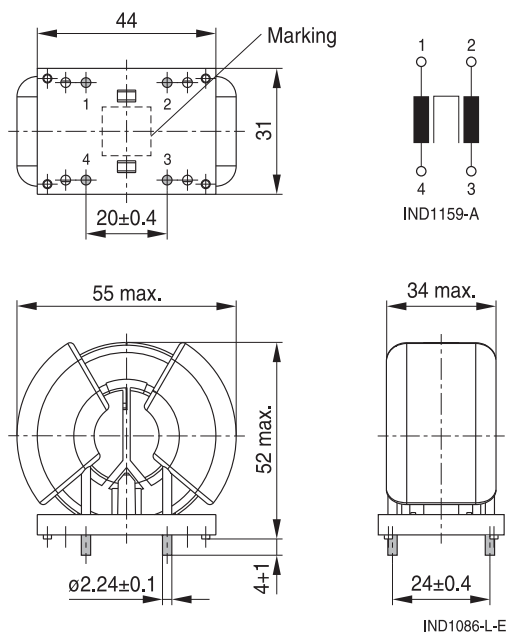
Size A



Tolerances to ISO 2768-cl / ISO 8015.
 Size ISO 14405 (E)
 All dimensions in mm

Size B

Version 1



Version 2



Tolerances to ISO 2768-cl / ISO 8015.
 Size ISO 14405 (E)
 All dimensions in mm

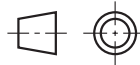
IND1245-O-E

Size C

Version 1

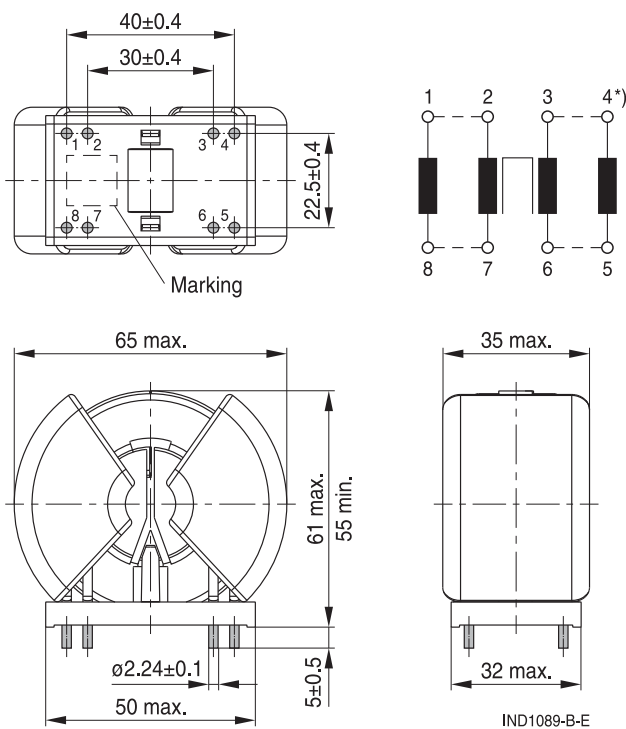


Tolerances to ISO 2768-cl / ISO 8015.
Size ISO 14405 (E)
All dimensions in mm



IND1245-O-E

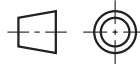
Version 2



*) Parallel wires must be shorted in application!

IND1160-B-E

Tolerances to ISO 2768-cl / ISO 8015.
Size ISO 14405 (E)
All dimensions in mm



IND1245-O-E

Technical data and measuring conditions

Rated voltage V_R	600 V AC (50 / 60 Hz) 1000 V DC
Test voltage V_{test}	3500 V DC, 2 s (line/line) 500 V DC, 1 s (parallel wires)
Rated temperature T_R	+70 °C
Rated current I_R	Referred to 50 Hz and rated temperature (shorted parallel wires in application)
Rated inductance L_R	Measured with Agilent 4284A at 0.1 mA, +20 °C Measuring frequency: $L_R \leq 1$ mH: $f = 100$ kHz $L_R > 1$ mH: $f = 10$ kHz Inductance is specified per winding
Inductance tolerance	-30/+50% at +20 °C
Inductance decrease $\Delta L/L_0$	< 10% at DC magnetic bias with I_R , +20 °C
Stray inductance $L_{stray,typ}$	Measured with Agilent 4284A at 5 mA, +20 °C, typical values Measuring frequency: $L_R \leq 1$ mH: $f = 100$ kHz $L_R > 1$ mH: $f = 10$ kHz
DC resistance R_{typ}	Measured at +20 °C, typical values, specified per winding and shorted parallel wires
Solderability (lead-free)	Sn96.5Ag3.0Cu0.5: +(245 ± 5) °C, (3 ± 0.3) s Wetting of soldering area ≥ 95% (to IEC 60068-2-20, test Ta)
Resistance to soldering heat (wave soldering)	+(260 ± 5) °C, (10 ± 1) s (to IEC 60068-2-20, test Tb)
Climatic category	40/125/56 (to IEC 60068-1)
Pollution degree	P2 (to IEC 61558-1)
Storage conditions (packaged)	-25 °C ... +40 °C, ≤ 75% RH
Approvals	UL1446 Class 155 (F) (E320370)

Characteristics and ordering codes
Size A

$I_{R,+70\text{ °C}}$ A	L_R mH	$L_{\text{stray,typ}}$ μH	R_{typ} m Ω	Weight approx. g	Ordering code
21	1.5	8.3	2.8	100	B82726E6213A040
24	1.0	5.7	2.3	90	B82726E6243A041
26	0.6	3.8	1.7	85	B82726E6263A040
29	0.44	2.9	1.5	80	B82726S6243A040 ¹⁾

1) Alternative rating: 24 A at +85 °C

Size B

$I_{R,+70\text{ °C}}$ A	L_R mH	$L_{\text{stray,typ}}$ μH	R_{typ} m Ω	Weight approx. g	Ordering code	Version	
						1	2
20	2.7	19	4.4	155	B82726E6203B041	X	—
24	1.5	11	3.2	135	B82726S6203A040 ¹⁾	X	—
28	1.0	7	2.1	140	B82726E6283B040	—	X
33	0.42	3.5	1.4	120	B82726E6333B040	—	X

1) Alternative rating: 20 A at +85 °C

Size C

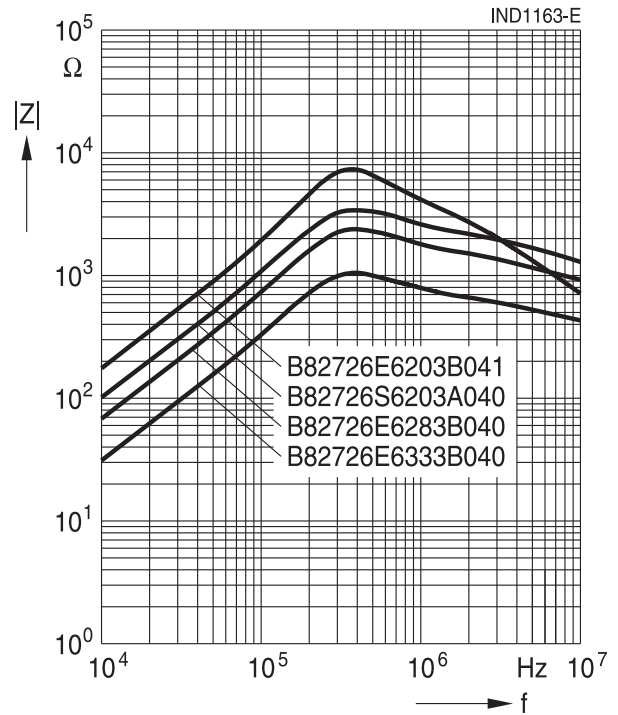
$I_{R,+70\text{ °C}}$ A	L_R mH	$L_{\text{stray,typ}}$ μH	R_{typ} m Ω	Weight approx. g	Ordering code	Version	
						1	2
22	3.3	20.0	4.6	210	B82727E6223A040	X	—
24	2.2	15.0	3.9	200	B82727E6243A040	X	—
40	1.5	9.0	1.7	245	B82727E6403A040	—	X
44	1.0	6.3	1.35	220	B82727E6443A040	—	X
50	0.57	3.7	1.0	200	B82727E6503A040	—	X

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Impedance $|Z|$ versus frequency f
measured with windings in parallel at +20 °C,
typical values



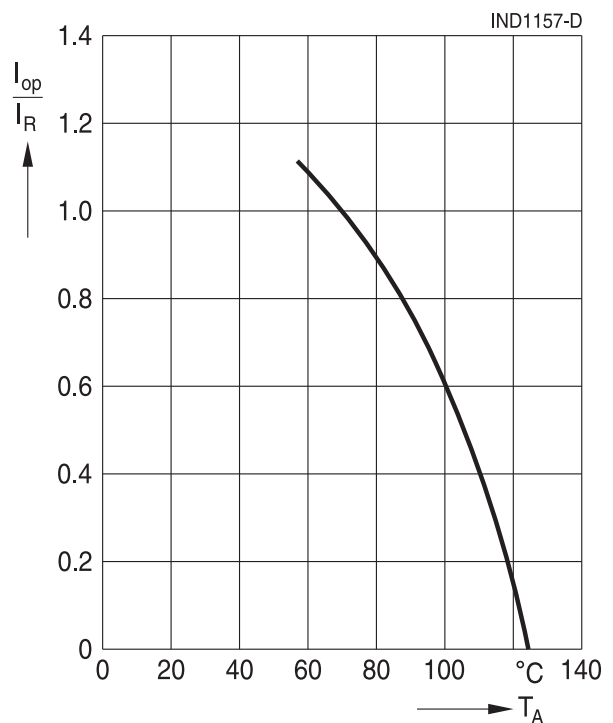
Impedance $|Z|$ versus frequency f
measured with windings in parallel at +20 °C,
typical values



Impedance $|Z|$ versus frequency f
measured with windings in parallel at +20 °C,
typical values



Current derating I_{op}/I_R
versus ambient temperature T_A
rated temperature $T_R = +70$ °C



Cautions and warnings

- Please note the recommendations in our Inductors data book (latest edition) and in the data sheets.
 - Particular attention should be paid to the derating curves given there.
 - The soldering conditions should also be observed. Temperatures quoted in relation to wave soldering refer to the pin, not the housing.
- If the components are to be washed varnished it is necessary to check whether the washing varnish agent that is used has a negative effect on the wire insulation, any plastics that are used, or on glued joints. In particular, it is possible for washing varnish agent residues to have a negative effect in the long-term on wire insulation.
Washing processes may damage the product due to the possible static or cyclic mechanical loads (e.g. ultrasonic cleaning). They may cause cracks to develop on the product and its parts, which might lead to reduced reliability or lifetime.
- The following points must be observed if the components are potted in customer applications:
 - Many potting materials shrink as they harden. They therefore exert a pressure on the plastic housing or core. This pressure can have a deleterious effect on electrical properties, and in extreme cases can damage the core or plastic housing mechanically.
 - It is necessary to check whether the potting material used attacks or destroys the wire insulation, plastics or glue.
 - The effect of the potting material can change the high-frequency behaviour of the components.
- Ferrites are sensitive to direct impact. This can cause the core material to flake, or lead to breakage of the core.
- Even for customer-specific products, conclusive validation of the component in the circuit can only be carried out by the customer.

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